								F	REVISI	ONS										
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A	Add and 7 Make	device 1.5. Ma e chanç	type 0 ake ch ge to T	2 testec anges t able IIB	d at low o footn and pa	/ dose / otes <u>2</u> / aragrap	ate. M and <u>3</u> / h 4.4.4	ake ch as spe I.1	ange to cified u rrp	o parag under T	raphs ' able I.	1.2.2,		11-()8-09			C. SA	FFLE	
В	Make unde CDFI	e corre r paraç P4-F16	ction to graph 1 5 ro	case c .2.4. A	outline I dd cas	etter F e outlir	descrip le X, de	otive de escriptiv	esignato ve desi	or as sp gnator	pecified	l		11-1	0-04			C. SA	FFLE	
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REV																				
SHEET																				
REV	В	В	В	В	В	В	В	В	В	В	В	В	В	В						
SHEET	15	16	17	18	19	20	21	22	23	24	25	26	27	28						
REV STATUS				REV	/		В	В	В	В	В	В	В	В	В	В	В	В	В	В
OF SHEETS				SHE	ET		1	2	3	4	5	6	7	8	9	10	11	12	13	14
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AND AGEN DEPARTMEN	ICIES (IT OF [OF THE	E ISE	DRA	WING	APPR(10-0)VAL D 94-27	DATE		SIL	ICON		RE MODULATOR, M				IONOLITHIC			
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					SHEET 1 OF 28															

1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 <u>PIN</u>. The PIN is as shown in the following example:



1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	<u>Generic number</u>	Circuit function
01	AD8346	Radiation hardened, 0.8 GHz to 2.5 GHz guadrature modulator
02	AD8346	Radiation hardened, 0.8 GHz to 2.5 GHz quadrature modulator

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as follows:

Device class	Device requirements documentation
Μ	Vendor self-certification to the requirements for MIL-STD-883 compliant, non- JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
F	GDFP2-F16	16	Flat pack
Х	CDFP4-F16	16	Flat pack

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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1.3 Absolute maximum ratings. 1/

	Supply voltage (VPS1, VPS2) Input power LOIP, LOIN (relative to 50 Ω) Input voltage IBBP, IBBN, QBBP, QBBN Power dissipation (P _D)	5.5 V 10 dBm 0 V to 2.5 V 340 mW
	Maximum junction temperature (T _J) Storage temperature range Lead temperature (soldering 60 seconds)	+150°C -65°C to +150°C +300°C
	Thermal resistance, junction to case (θ_{JC})	38°C/W 64°C/W <u>2</u> /
1.4	A Recommended operating conditions.	
	Supply voltage (VPS1, VPS2) Ambient operating temperature range (T _A)	2.7 to 5.25 V -55°C to +125°C
1.5	5 Radiation features:	
	Device type 01: Maximum total dose available (dose rate = 50 – 300 rads(Si)/s) 100 krad Device type 02: Maximum total dose available (dose rate ≤ 10 mrads(Si)/s)	ds (Si) <u>3</u> / s (Si) 4/

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits. MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at https://assist.daps.dla.mil/quicksearch/ or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ Measurement taken under absolute worst case conditions of still air.

- 3/ These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, method 1019, condition A.
- <u>4</u>/ For device type 02, radiation end point limits for the noted parameters are guaranteed for the conditions specified in MIL-STD-883, method 1019, condition D.

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2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 <u>Case outline</u>. The case outline shall be in accordance with 1.2.4 herein.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.

3.2.3 <u>Block diagram</u>. The timing waveforms shall be as specified on figure 2.

3.2.4 <u>Radiation exposure circuit</u>. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 <u>Notification of change for device class M</u>. For device class M, notification to DLA Land and Maritime -VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 <u>Verification and review for device class M</u>. For device class M, DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 110 (see MIL-PRF-38535, appendix A).

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Test	Symbol	Conditio -55°C ≤ 1 unless othe	ons <u>1/ 2</u> / <u>3</u> / Г _A ≤ +125°C rwise specified	Group A subgroups	Device type	Limits		Unit
						Min	Max	_
RF OUTPUT section.	V _{PS} = 5 '	V; f _{LO} = LO fre	quency = 800 Mł	Hz, LO input le	evel = -6 dB	m <u>4</u> /	1	1
Output power	POUT	Single (lowe	r) sideband,	4	01, 02	-11	-4	dBm
		f _{LO} - f _{BB}		5		-11	-4	
				6		-11	-4	
			M,D,P,L,R	4	01	-11	4	
			M,D,P,L	4	02	-11	4	
Carrier feedthrough	P _{FDTH}	fLO		4	01, 02		-35	dBm
				5			-35	
				6			-35	
			M,D,P,L,R	4	01		-35	
			M,D,P,L	4	02		-35	
Sideband suppression	PSUPP	f _{LO} + f _{BB}	•	4	01, 02		-28	dBc
				5			-28	
				6			-30	
			M,D,P,L,R	4	01		-28	
			M,D,P,L	4	02		-28	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02		-46	dBc
				5			-49	
				6			-45	
			M,D,P,L,R	4	01		-46	
			M,D,P,L	4	02		-46	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}	1	4	01, 02		-49	dBc
				5	1		-48	1
				6	-		-48	
			M,D,P,L,R	4	01		-49	
			M,D,P,L	4	02		-49	
See footnotes at end of tabl	e.							
STA MICROCIRC	NDARD CUIT DRAV	VING	SI	ZE A			59	62-092
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990				RE	VISION LEVE B	ΞL	SHEET	г 5

		$\begin{array}{l} Conditions \ \underline{1}/\underline{2}/\underline{3}/\\ -55^\circ C \leq T_A \leq +125^\circ C\\ unless \ otherwise \ specified \end{array}$		Device type	Limits		Unit
					Min	Max	
nued. Vps	s = 5 V; f _{LO} = L	O frequency = 8	00 MHz, LO in	put level =	-6 dBm	<u>4</u> /	1
P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-45	dBc
			5	-		-47	_
			6			-42	_
		M,D,P,L,R	4	01		-45	_
		M,D,P,L	4	02		-45	
RF OUTPUT section .		_O = LO frequenc	cy = 1.9 GHz, L	O input le	vel = -6 d	Bm <u>4</u> /	
POUT	Single (lower) sideband,	4	01, 02	-13	-6	dBm
	f _{LO} - f _{BB}		5		-18	-8	
			6		-13	-6	
		M,D,P,L,R	4	01	-13	-6	
		M,D,P,L	4	02	-13	-6	
PFDTH	fLO		4	01, 02		-35	dBm
			5			-35	
			6			-35	
		M,D,P,L,R	4	01		-35	
		M,D,P,L	4	02		-35	
PSUPP	f _{LO} + f _{BB}		4	01, 02		-25	dBc
			5			-25	
			6			-26	
		M,D,P,L,R	4	01		-25	1
		M,D,P,L	4	02		-25	
P _{2ndL}	f _{LO} - 2f _{BB}	•	4	01, 02		-45	dBc
			5	-		-44	
			6	-		-45	
		M,D,P,L,R	4	01		-45	
		M,D,P,L	4	02		-45	
_	POUT POUT PFDTH PSUPP	P3rdU ILO + 3IBB VPS = 5 V; fL POUT POUT Single (lower fLO - fBB PFDTH fLO PSUPP fLO + fBB P2ndL fLO - 2fBB	P3rdUILO + 3IBBM,D,P,L,RM,D,P,L,RM,D,P,LPOUTSingle (lower) sideband, fLO - fBBPOUTM,D,P,L,RM,D,P,L,RM,D,P,LPFDTHfLOM,D,P,L,RM,D,P,LPSUPPfLO + fBBM,D,P,L,RM,D,P,LP2ndLfLO - 2fBBM,D,P,L,RM,D,P,L,RM,D,P,L,RM,D,P,L,RM,D,P,L,RM,D,P,L	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{ c c c c c c c } & $	$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $

	TABLE	I. Electrical pe	rformance chara	acteristics – co	ntinued.			
Test	Symbol	Condition -55°C ≤ T unless other	ns <u>1/ 2/ 3</u> / A ≤ +125°C wise specified	Group A subgroups	Device type	Limits Min Max		Unit
RF OUTPUT section - cont	inued.	V _{PS} = 5 V; f _L	O = LO frequenc	cy = 1.9 GHz,	LO input lev	vel = -6 d	Bm <u>4</u> /	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02		-45	dBc
				5	_		-46	_
				6			-46	_
			M,D,P,L,R	4	01		-45	_
		M,D,P,L	4	02		-45		
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-46	dBc
				5			-50	_
				6			-41	
			M,D,P,L,R	4	01		-46	
			M,D,P,L	4	02		-46	
RF OUTPUT section.		V _{PS} = 5 V; f _L	O = LO frequenc	cy = 2.3 GHz,	LO input lev	vel = -6 d	Bm <u>4</u> /	
Output power	Pout	Single (lower) sideband,	4	01, 02	-16	-7	dBm
		f _{LO} - f _{BB}		5		-23	-10	
				6		-14	-7	
			M,D,P,L,R	4	01	-16	-7	
			M,D,P,L	4	02	-16	-7	
Carrier feedthrough	Pfdth	fLO		4	01, 02		-34	dBm
				5			-35	
				6	-		-34	
			M,D,P,L,R	4	01		-34	
			M,D,P,L	4	02		-34	
Sideband suppression	PSUPP	f _{LO} + f _{BB}	<u>.</u>	4	01, 02		-25	dBc
				5			-25	
				6	-		-26	
			M,D,P,L,R	4	01		-25	
			M,D,P,L	4	02		-25	
See footnotes at end of tab	le.				,			
STA MICROCIRO	NDARD CUIT DRAW	/ING	SI.	ZE A			59	62-0922
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	TABLE	I. Electrical pe	erformance chara	acteristics – co	ntinued.			
Test	Symbol	Conditions $1/2/3/$ -55°C \leq T _A \leq +125°C unless otherwise specified		Group A subgroups	Device type	Limits		Unit
RF OUTPUT section - cont	inued.	$V_{PS} = 5 V$ f	$\alpha = 10$ frequence	cv = 2 3 GHz	l O input lev	Min vel = -6 d	Max Bm 4/	
Second lower harmonic	Pond	fi o - 2fpp		4	01, 02		-45	dBc
	' ZHUL	10 2100		5	-		-42	
				6	-		-42	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	_
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02		-45	dBc
				5	-		-44	
				6			-45	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-48	dBc
				5			-47	
				6			-43	
			M,D,P,L,R	4	01		-48	
			M,D,P,L	4	02		-48	
RF OUTPUT section.		V _{PS} = 5 V; f _L	_O = LO frequenc	cy = 800 MHz,	LO input le	evel = -12	dBm <u>4</u> /	
Output power	Pout	Single (lower	r) sideband,	4	01, 02	-11	-4	dBm
		f _{LO} - f _{BB}		5		-11	-4	
				6		-11	-4	
			M,D,P,L,R	4	01	-11	4	
			M,D,P,L	4	02	-11	4	
Carrier feedthrough	P _{FDTH}	fLO		4	01, 02		-35	dBm
				5			-35	
				6			-35	
			M,D,P,L,R	4	01		-35	_
			M,D,P,L	4	02		-35	
See footnotes at end of tab	le.							
STA MICROCIRO	NDARD CUIT DRAW	VING	SI.	ZE A			59	62-0922
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	TABLE	I. Electrical per	rforman	ce chara	acteristics	- continued.			
Test	Symbol	Condition -55°C \leq T $_{\ell}$ unless other	ns <u>1/ 2</u> / _A ≤ +12 wise spe	<u>3</u> / 5°C ecified	Group subgrou	A Device ips type	Lir	nits Max	Unit
RF OUTPUT section – cont	inued.	V _{PS} = 5 V; f _{LC}) = LO f	requenc	y = 800 M	Hz, LO input l	evel = -12	dBm <u>4</u> /	L
Sideband suppression	PSUPP	f _{LO} + f _{BB}			4	01, 02		-28	dBc
					5			-28	
					6			-30	
			M,D,F	P,L,R	4	01		-28	
			M,D,F	P,L	4	02		-28	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}			4	01, 02		-42	dBc
					5			-45	
					6			-45	
			M,D,F	P,L,R	4	01		-42	
			M,D,F	P,L	4	02		-42	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}			4	01, 02		-45	dBc
					5			-45	
					6			-45	
			M,D,F	P,L,R	4	01		-45	
			M,D,F	P,L	4	02		-45	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}			4	01, 02		-45	dBc
					5			-48	
					6			-43	
			M,D,F	P,L,R	4	01		-45	
			M,D,F	P,L	4	02		-45	
RF OUTPUT section.		V _{PS} = 5 V; f _L	0 = LO 1	frequenc	cy = 1.9 G	Hz, LO input le	evel = -12	dBm <u>4/ </u>	<u>5/</u>
Output power	POUT	Single (lower)) sideba	nd,	4	01, 02	-13	-6	dBm
		f _{LO} - f _{BB}			5		-26	-10	
					6		-13	-6	
			M,D,F	P,L,R	4	01	-13	-6	
			M,D,F	P,L	4	02	-13	-6	
See footnotes at end of table	e.								
STA MICROCIRC	NDARD UIT DRAW	/ING		SIZ J	ZE			59	62-09227
DLA LAND / COLUMBUS, (DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990					REVISION LEV B	ΈL	SHEET	9

		Conditio	ns 1/2/3/				
Test	Symbol	-55°C ≤ 1 unless othe	Γ _A ≤ +125°C rwise specified	Group A subgroups	Device type	Limits	Unit
				earg.eape	.960	Min Max	-
RF OUTPUT section - contin	nued.	V _{PS} = 5 V; f _l	LO = LO frequenc	cy = 1.9 GHz,	LO input lev	/el = -12 dBm <u>4</u> / <u>5</u>	5/
Carrier feedthrough	P _{FDTH}	fLO		4	01, 02	-35	dBm
				5		-38	
				6		-35	
			M,D,P,L,R	4	01	-35	
			M,D,P,L	4	02	-35	
Sideband suppression	P _{SUPP}	f _{LO} + f _{BB}		4	01, 02	-25	dBc
				5		-25	
				6		-26	
			M,D,P,L,R	4	01	-25	
			M,D,P,L	4	02	-25	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02	-42	dBc
				5		-41	
				6		-42	
			M,D,P,L,R	4	01	-42	
			M,D,P,L	4	02	-42	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}	·	4	01, 02	-45	dBc
				5		-44	-
				6		-45	
			M,D,P,L,R	4	01	-45	
			M,D,P,L	4	02	-45	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}	·	4	01, 02	-49	dBc
				5		-49	
				6	_	-43	
			M,D,P,L,R	4	01	-49	
			M,D,P,L	4	02	-49	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}	M,D,P,L,R M,D,P,L M,D,P,L,R M,D,P,L	4 4 4 5 6 4 4	01 02 01, 02 01 01 02		-45 -45 -49 -49 -49 -43 -49 -49 -49 -49
e.	M,D,P,L,R 4 M,D,P,L 4	6 M,D,P,L,R 4 M,D,P,L 4	6 4 4		01 02	-43 -49 -49	-
STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME			SIZ L	ZE A RE\	/ISION LEVE	590	62-092

- .		Conditio	ons <u>1/2/3/</u>				.,	
Test	Symbol	-55°C ≤ I unless othe	$A \le +125^{\circ}C$ rwise specified	Group A subgroups	Device type	Lir	nits	Unit
						Min	Max	
RF OUTPUT section.		V _{PS} = 5 V; f _l	LO = LO frequenc	cy = 2.3 GHz,	LO input le	vel = -12	dBm <u>4/5</u>	5/
Output power	Pout	Single (lower	r) sideband,	4	01, 02	-17	-8	dBm
		f _{LO} - f _{BB}		5		-32	-15	_
				6		-15	-8	-
			M,D,P,L,R	4	01	-17	-8	_
			M,D,P,L	4	02	-17	-8	
Carrier feedthrough	P _{FDTH}	f _{LO}		4	01, 02		-35	dBm
				5			-40	
				6			-35	
			M,D,P,L,R	4	01		-35	
			M,D,P,L	4	02		-35	
Sideband suppression	PSUPP	f _{LO} + f _{BB}		4	01, 02		-25	dBc
				5			-25	
				6			-26	
			M,D,P,L,R	4	01		-25	
			M,D,P,L	4	02		-25	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02		-43	dBc
				5			-40	
				6			-40	
			M,D,P,L,R	4	01		-43	
			M,D,P,L	4	02		-43	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02		-45	dBc
				5			-42	
				6			-45	-
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
See footnotes at end of tabl	e.							
STA MICROCIRC	NDARD CUIT DRAW	/ING	SI	ZE A			590	62-092:
DLA LAND A COLUMBUS,	DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990			RE\	ISION LEVE/ B	EL	SHEET	11

RF OUTPUT section – conti		$-55^{\circ}C \le T_A \le +125^{\circ}C$ unless otherwise specified		Group A subgroups	Device type	Limits		Unit
RF OUTPUT section – conti						Min	Max	
	nued.	V _{PS} = 5 V; f _L	O = LO frequenc	cy = 2.3 GHz,	LO input le	vel = -12	dBm <u>4/ </u> 5	5/
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-47	dBc
				5			-43	
				6			-45	
			M,D,P,L,R	4	01		-47	
			M,D,P,L	4	02		-47	
RF OUTPUT section.		V _{PS} = 3 V; f _L	O = LO frequenc	cy = 800 MHz,	LO input le	evel = -6 d	dBm <u>4</u> /	
Output power	POUT	Single (lower) sideband,	4	01, 02	-11	-4	dBm
		f _{LO} - f _{BB}		5		-11	-4	
				6		-11	-4	
			M,D,P,L,R	4	01	-11	4	
			M,D,P,L	4	02	-11	4	
Carrier feedthrough	PFDTH	fLO	-	4	01, 02		-35	dBm
				5		2	-35	
				6			-35	
			M,D,P,L,R	4	01	-35	-35	
			M,D,P,L	4	02		-35	
Sideband suppression	PSUPP	fLO + fBB		4	01, 02		-28	dBc
				5	-		-28	
				6	-		-30	
			M,D,P,L,R	4	01		-28	
			M,D,P,L	4	02		-28	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02		-46	dBc
		-		5	-		-49	
				6	-		-45	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
See footnotes at end of table	9.							
STANDARD MICROCIRCUIT DRAWING			SI	ZE A			59	62-092

	TABLE	I. Electrical pe	erformance chara	acteristics – co	ntinued.			
Test	Symbol	Conditio $-55^{\circ}C \le T$ unless other	ns <u>1/ 2</u> / <u>3</u> / A ≤ +125°C wise specified	Group A subgroups	Device type	Liı	mits	Unit
						Min	Max	
RF OUTPUT section – con	tinued.	V _{PS} = 3 V; f _L	_O = LO frequen	cy = 800 MHz,	LO input le	evel = -6	dBm <u>4</u> /	
Second upper harmonic	P _{2ndU}	f_{LO} + $2f_{BB}$		4	01, 02		-49	dBc
				5	_		-48	_
				6			-48	_
			M,D,P,L,R	4	01		-49	_
			M,D,P,L	4	02		-49	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-45	dBc
				5			-44]
				6			-40	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
RF OUTPUT section .	·	V _{PS} = 3 V; f	LO = LO frequen	icy = 1.9 GHz,	LO input le	evel = -6 o	dBm <u>4</u> /	
Output power	Роит	Single (lower) sideband,	4	01, 02	-13	-6	dBm
		f _{LO} - f _{BB}		5	1	-18	-8	
		-		6	1	-13	-6	
			M,D,P,L,R	4	01	-13	-6	-
			M,D,P,L	4	02	-13	-6	
Carrier feedthrough	Рертн	fio		4	01, 02		-35	dBm
		20		5	1		-35	-
				6	-		-35	-
			M,D,P,L,R	4	01		-35	-
			M,D,P,L	4	02		-35	
Sideband suppression	Psupp	fun + fee		4	01, 02		-25	dBc
	· 30FF	1LO 1 1BB		5	-		-25	-
				6	1		-26	-
			M,D,P,L,R	4	01		-25	-
			M,D,P,L	4	02		-25	-
See footnotes at end of tab	le.				1	I	<u> </u>	1
STANDARD MICROCIRCUIT DRAWING			SI	ZE A			590	62-0922
DLA LAND COLUMBUS,	DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990			REV	ISION LEVE	EL	SHEET	13

Test	Symbol	Condition $-55^{\circ}C \leq T_{e}$ unless other	ns <u>1/ 2/ 3</u> / _A ≤ +125°C wise specified	Group A subgroups	Device type	Lir	nits	Unit
						Min	Max	
RF OUTPUT section – cont	inued.	V _{PS} = 3 V; f _L	_O = LO frequen	cy = 1.9 GHz,	LO input le	evel = -6 c	IBm <u>4</u> /	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02		-45	dBc
				5	_		-44	_
				6			-45	_
			M,D,P,L,R	4	01		-45	_
			M,D,P,L	4	02		-45	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02		-45	dBc
				5			-45	
				6			-46	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-45	dBc
				5			-47	
				6			-41	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
RF OUTPUT section.	·	V _{PS} = 3 V; f _L	o = LO frequenc	cy = 2.3 GHz, I	O input lev	/el = -6 d	Bm <u>4</u> /	
Output power	POUT	Single (lower)) sideband,	4	01, 02	-17	-8	dBm
		f _{LO} - f _{BB}		5		-24	-11	
				6	-	-15	-8	
			M,D,P,L,R	4	01	-17	-8	
			M,D,P,L	4	02	-17	-8	
Carrier feedthrough	P _{FDTH}	f _{LO}		4	01, 02		-34	dBm
		_		5	1		-36	1
				6	1		-34	1
			M,D,P,L,R	4	01		-34	1
			M,D,P,L	4	02		-34	1
See footnotes at end of tabl	e.							I
STANDARD MICROCIRCUIT DRAWING			SI I	ZE A			59	62-092
DLA LAND / COLUMBUS,	DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990			REV	'ISION LEVE B	L	SHEET	14

	TABLE	I. Electrical pe	erformance chara	acteristics –	continued.			
Test	Symbol	Conditio -55°C \leq T unless other	ons <u>1/ 2</u> / <u>3</u> / ¯ _A ≤ +125°C rwise specified	Group A subgroups	Device s type	Lir	nits	Unit
						Min	Max	
RF OUTPUT section - conti	inued.	V _{PS} = 3 V; f _L	_O = LO frequen	cy = 2.3 GHz	z, LO input le	vel = -6 d	Bm <u>4</u> /	
Sideband suppression	PSUPP	f _{LO} + f _{BB}		4	01, 02		-25	dBc
				5			-25	
				6			-26	
			M,D,P,L,R	4	01		-25	
			M,D,P,L	4	02		-25	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02		-45	dBc
				5			-42	
				6			-42	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02		-45	dBc
				5			-43	-
				6			-45	-
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
Third upper harmonic	Pardu	fi o + 3f _{BB}		4	01, 02		-47	dBc
				5			-47	-
				6			-43	
			M,D,P,L,R	4	01		-47	
			M,D,P,L	4	02		-47	
RF OUTPUT section.		VPS = 3 V; fi	o = LO frequen	cy = 800 MH	Iz, LO input le	evel = -12	dBm 4/	
Output power	Ронт	Single (lower	r) sideband,	4	01, 02	-11	-4	dBm
		f _{LO} - f _{BB}		5		-11	-4	1
		20 22		6		-11	-4	-
			M,D,P,L,R	4	01	-11	4	
			M,D,P,L	4	02	-11	4	
See footnotes at end of tabl	le.							
STA MICROCIRC	NDARD CUIT DRAW	/ING	SI	ZE A			59	62-0922
DLA LAND COLUMBUS,	AND MARITIN OHIO 43218-3	ИЕ 3990		R	EVISION LEVI B	ΞL	SHEET	- 15

Test	Symbol	Conditions <u>1</u> / <u>2</u> / <u>3</u> / -55°C \leq T _A \leq +125°C unless otherwise specified		Group A subgroups	Device type	Limits	Unit
				0g.0p0	.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	Min Max	-
RF OUTPUT section – conti	nued.	V _{PS} = 3 V; f _l	LO = LO frequen	cy = 800 MHz,	LO input le	vel = -12 dBm <u>4</u> /	
Carrier feedthrough	P _{FDTH}	fLO		4	01, 02	-35	dBm
				5		-35	
				6		-35	
			M,D,P,L,R	4	01	-35	
			M,D,P,L	4	02	-35	
Sideband suppression	P _{SUPP}	f _{LO} + f _{BB}		4	01, 02	-28	dBc
				5		-28	
				6		-30	
			M,D,P,L,R	4	01	-28	
			M,D,P,L	4	02	-28	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02	-42	dBc
				5		-45	
				6		-45	
			M,D,P,L,R	4	01	-42	
			M,D,P,L	4	02	-42	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02	-45	dBc
				5		-45	
				6		-45	
			M,D,P,L,R	4	01	-45	
			M,D,P,L	4	02	-45	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02	-45	dBc
				5		-44	
				6		-41	
			M,D,P,L,R	4	01	-45	
			M,D,P,L	4	02	-45	

								1
Test	Symbol	Conditio -55°C ≤ T unless othe	ons <u>1/ 2/ 3</u> / Γ _A ≤ +125°C rwise specified	Group A subgroups	Device type	Lir	mits	Unit
			ľ	U		Min	Max	-
RF OUTPUT section.		V _{PS} = 3 V; f _l	LO = LO frequenc	cy = 1.9 GHz,	LO input le	vel = -12	dBm <u>4</u> /	<u>5</u> /
Output power	POUT	Single (lowe	r) sideband,	4	01, 02	-14	-7	dBm
		f _{LO} - f _{BB}		5		-26	-10	
				6		-14	-7	
			M,D,P,L,R	4	01	-14	-7	
			M,D,P,L	4	02	-14	-7	
Carrier feedthrough	P _{FDTH}	f _{LO}		4	01, 02		-35	dBm
				5			-38	
				6			-35	
			M,D,P,L,R	4	01		-35	
			M,D,P,L	4	02		-35	
Sideband suppression	PSUPP	f _{LO} + f _{BB}		4	01, 02		-25	dBc
				5			-25	
				6			-26	
			M,D,P,L,R	4	01		-25	
			M,D,P,L	4	02		-25	
Second lower harmonic	P _{2ndL}	f _{LO} - 2f _{BB}		4	01, 02		-42	dBc
				5			-41	
				6			-42	
			M,D,P,L,R	4	01		-42	
			M,D,P,L	4	02		-42	
Second upper harmonic	P _{2ndU}	f _{LO} + 2f _{BB}		4	01, 02		-45	dBc
				5			-43	
				6			-45	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
See footnotes at end of tabl	e.							
STA MICROCIRC	NDARD CUIT DRAW	/ING	SI	ZE A			59	62-092:
DLA LAND COLUMBUS,	AND MARITIN OHIO 43218-3	ИЕ 3990		REV	ISION LEVE/ B	ΞL	SHEET	- 17

Test	Symbol	Conditio -55°C ≤ 1 unless othe	ons <u>1/ 2/ 3</u> / 「 _A ≤ +125°C rwise specified	Group A subgroups	Device type	Li	mits	Unit
						Min	Max	_
RF OUTPUT section - cont	inued.	V _{PS} = 3 V; f _l	_O = LO frequenc	cy = 1.9 GHz	, LO input le	vel = -12	dBm <u>4/5</u>	5/
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-48	dBc
				5			-49	
			_	6			-43	
			M,D,P,L,R	4	01		-48	
			M,D,P,L	4	02		-48	
RF OUTPUT section.		V _{PS} = 3 V; f _l	_o = LO frequend	cy = 2.3 GHz	, LO input le	vel = -12	dBm <u>4/5</u>	<u>5</u> /
Output power	Pout	Single (lowe	r) sideband,	4	01, 02	-18	-9	dBm
		f _{LO} - f _{BB}		5		-32	-15	
				6		-17	-9	
			M,D,P,L,R	4	01	-18	-9	
			M,D,P,L	4	02	-18	-9	
Carrier feedthrough	PFDTH	fLO		4	01, 02		-35	dBm
				5			-41	
				6	_		-41 -35 -35 -35	
			M,D,P,L,R	4	01		-35	-
			M,D,P,L	4	02		-35	
Sideband suppression	PSUPP	f _{LO} + f _{BB}		4	01, 02		-25	dBc
				5			-25	-
				6			-26	-
			M,D,P,L,R	4	01		-25	
			M,D,P,L	4	02		-25	-
Second lower harmonic	P _{2ndl}	fi o - 2f _{BB}		4	01, 02		-43	dBc
				5			-40	-
				6	_		-40	-
			M,D,P,L,R	4	01		-43	-
			M,D,P,L	4	02	2 -43	-43	-
See footnotes at end of tab	le.							
STANDARD MICROCIRCUIT DRAWING			SI	ZE A			59	62-092:
DLA LAND COLUMBUS,	AND MARITIN OHIO 43218-	DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990			EVISION LEVE B	ΞL	SHEET	18

RF OUTPUT section – cont		$\label{eq:constraint} \begin{array}{l} -55^\circ C \leq T_A \leq +125^\circ C \\ \text{unless otherwise specified} \end{array}$		Group A subgroups	Device type	Limits		Unit
RF OUTPUT section - cont						Min	Max	
	inued.	V _{PS} = 3 V; f _L	O = LO frequenc	y = 2.3 GHz,	LO input lev	/el = -12	dBm <u>4/ </u>	<u>5</u> /
Second upper harmonic	P2ndU	fLO + 2fBB		4	01, 02		-45	dBc
				5			-41	
				6			-45	
			M,D,P,L,R	4	01		-45	
			M,D,P,L	4	02		-45	
Third upper harmonic	P _{3rdU}	f _{LO} + 3f _{BB}		4	01, 02		-47	dBc
				5			-44	
				6			-44	
			M,D,P,L,R	4	01		-47	
			M,D,P,L	4	02		-47	
ENABLE input section		V _{PS} = 3 V; V	PS = 5 V					1
ENABLE high threshold	VIH			1,2,3	01, 02	2.0		V
voltage			M,D,P,L,R	1	01	2.0		
			M,D,P,L	1	02	2.0		
ENBLE low threshold	VIL			1,2,3	01, 02		0.5	V
voltage			M,D,P,L,R	1	01		0.5	
			M,D,P,L	1	02		0.5	
ENABLE low threshold	IIL _{0V}	V _{IL} = 0 V		1,2,3	01, 02		1	μA
current			M,D,P,L,R	1	01		1	
			M,D,P,L	1	02		1	
ENABLE low threshold	IIL _{0.5V}	V _{IL} = 0.5 V	·	1,2,3	01, 02		10	μΑ
current			M,D,P,L,R	1	01		10	
			M,D,P,L	1	02		10	
ENABLE high threshold	I _{IH2V}	V _{IH} = 2 V		1,2,3	01, 02		60	μA
current			M,D,P,L,R	1	01		60	
			M,D,P,L	1	02		60	
See footnotes at end of tabl	e.							
STANDARD MICROCIRCUIT DRAWING			siz L	ZE			59	62-092

Test	Symbol	Condition $-55^{\circ}C \leq T_{\mu}$ unless other	ns <u>1/ 2/ 3</u> / ₄ ≤ +125°C wise specified	Group A subgroups	Device type	Li	mits	Unit
						Min	Max	
ENABLE input section - cont	inued	V _{PS} = 3 V; V _P	_S = 5 V				1	
ENABLE high threshold	I _{IH3V}	$V_{IH} = V_{PS} = 3$	3 V	1,2,3	01, 02		100	μA
current			M,D,P,L,R	1	01		100	_
			M,D,P,L	1	02		100	
ENABLE high threshold	I _{IH5V}	$V_{IH} = V_{PS} = 5$	5 V	1,2,3	01, 02		180	μA
current			M,D,P,L,R	1	01		180	
			M,D,P,L	1	02		180	
ENABLE turn on <u>6</u> / <u>7</u> /	tON	See 4.4.1c		9,11	01, 02		3	μS
time				10			8	
ENABLE turn off 6/7/	tOFF	See 4.4.1c		9,11	01, 02		15	μS
time				10	_		20	-
Modulation input section		VPS = 3 V; VF	ps = 5 V	I				
Input resistance 6/ 7/	RIN	See 4.4.1d	0	1,2,3	01, 02	12	15	kΩ
Modulation bandwidth 6/7/	BW	-3 dB, see 4.4	1.1d	4,5,6	01, 02	30		MHz
Power supply section								
/ positive supply current IPS3V		VPS = 3 V,		1	01, 02	33	53	mA
		ENABLE = 2	V	2	_	40	60	1
				3		24	44	-
			M,D,P,L,R	1	01	33	53	1
			M,D,P,L	1	02	33	53	-
5 V positive supply current	IPS5V	VPS = 5 V.		1	01, 02	35	55	mA
	1000	ENABLE = 2	V	2		42	62	-
				3		25	45	-
			M.D.P.L.R	1	01	35	55	-
			M,D,P,L	1	02	35	55	-
See footnotes at end of table.								1
STANDARD MICROCIRCUIT DRAWING			SI.	ZE A			59	62-0922
DLA LAND AI COLUMBUS, O	DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990			RE	VISION LEVE B	EL	SHEET	. 20

Test	Symbol	$\begin{array}{c} \mbox{Conditions} \ \underline{1/2/3} \\ \mbox{Symbol} \\ \ -55^{\circ}C \leq T_A \leq +125^{\circ}C \\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $		Group A subgroups	Device type	Limits		Unit
						Min	Max	
Power supply section – con	tinued.							
Maximum positive supply current		V _{PS} = 5.25 V,		1	01, 02	35	55	mA
		ENABLE = 2 V		2		42	62	
				3		25	45	
			M,D,P,L,R	1	01	35	55	
			M,D,P,L	1	02	35	55	
Standby positive supply current	I _{Standby}	V _{PS} = 3 V; V _F ENABLE = 0.	ps = 5 V; 5 V	1,2,3	01, 02		20	μΑ
			M,D,P,L,R	1	01		20	
			M,D,P,L	1	02		20	

2/ Device type 01 supplied to this drawing has been characterized through all levels M, D, P, L, R of irradiation. Device type 02 supplied to this drawing has been characterized through all levels M, D, P, L of irradiation. However, device type 01 is only tested at the "R" level and device type 02 is only tested at the "L" level. Pre and Post irradiation values are identical unless otherwise specified in Table I. When performing post irradiation electrical measurements for any RHA level, T_A = +25°C.

3/ For device type 01, this part may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A for device type 01 and condition D for device type 02. Device type 02, has been tested at low dose rate.

4/ f_{LO} = 2.5 GHz operation is achievable but not production tested. Contact manufacturer for more information.

- 5/ For increased subgroup 5 output power at $f_{LO} = 1.9$ GHz and $f_{LO} = 2.3$ GHz, use LO input level of -6 dBm.
- 6/ Not tested post irradiation.
- $\underline{7}$ Parameter tested as part of device initial characterization and after design and process changes. BB input level = 0.9 Vp-p each input for 1.8 Vp-p differential drive.

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Device types	01 and 02
Case outlines	F and X
Terminal number	Test symbol
1	IBBP
2	IBBN
3	COM1
4	COM1
5	LOIN
6	LOIP
7	VPS1
8	ENBL
9	COM2
10	COM3
11	VOUT
12	VPS2
13	COM4
14	COM4
15	QBBN
16	QBBP

FIGURE 1. Terminal connections.

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Terminal symbol	Туре	Description
COM4	Ground	Ground pin for the baseband input voltage to current converters and mixer core.
IBBP	Analog input	I channel baseband positive input pin. Input should be DC-biased to 1.2 V. Nominal characterized AC swing is 1 V _{p-p} (0.7 V to 1.7 V). This makes the differential input 2 V _{p-p} when IBBN is 180 degrees out of phase from IBBP.
IBBN	Analog input	I channel baseband negative input pin. Input should be DC-biased to 1.2 V. Nominal characterized AC swing is 1 V _{p-p} (0.7 V to 1.7 V). This makes the differential input 2 V _{p-p} when IBBN is 180 degrees out of phase from IBBP.
COM1	Ground	Ground pin for the local oscillator (LO) phase splitter and LO buffers.
LOIN	Analog input	LO negative input pin. Internal dc bias (approximately VPS1 to 800 mV) is supplied. This pin must be AC-coupled.
LOIP	Analog input	LO positive input pin. Internal dc bias (approximately VPS1 to 800 mV) is supplied. This pin must be AC-coupled.
VPS1	Power	Power supply pin for the bias cell and LO buffers. This pin should be decoupled using local 100 pF and 0.01μ F capacitors. Must be externally connected to VPS2.
ENBL	Digital input	Enable pin. A high level enables the device; a low level puts the device in sleep mode.
COM2	Ground	Ground pin for the input stage of the output amplifier.
COM3	Ground	Ground pin for the output stage of the output amplifier.
VOUT	Analog output	50 Ω DC-coupled RF output. User must provide AC coupling on this pin.
VPS2	Power	Power supply pin for baseband input voltage to current converters and mixer core. This pin should be decoupled using local 100 pF and 0.01 μ F capacitors. Must be externally connected to VPS1.
QBBP	Analog input	Q channel baseband positive input pin. Input should be DC- biased to 1.2 V. Nominal characterized AC swing is 1 V _{p-p} (0.7 V to 1.7 V). This makes the differential input 2 V _{p-p} when QBBN is 180 degrees out of phase from QBBP.
QBBN	Analog input	Q channel baseband negative input pin. Input should be DC-biased to 1.2 V. Nominal characterized AC swing is 1 V_{p-p} (0.7 V to 1.7 V). This makes the differential input 2 V_{p-p} when QBBN is 180 degrees out of phase from QBBP.

FIGURE 1. <u>Terminal connections</u> – continued.

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4. VERIFICATION

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 9, 10, and 11 are tested as part of device initial characterization and after design and process changes.
- d. RIN and BW are tested as part of device initial characterization and after design and process changes.

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Test requirements	Subgroups	Su	bgroups
	(in accordance with	(in accordance with	
	MIL-STD-883,	MIL-PRF-38535, table III)	
	method 5005, table I)		
	Device	Device	Device
	class M	class Q	class V
Interim electrical	1	1	1
parameters (see 4.2)			
Final electrical	1,2,3,4,5,6 <u>1</u> /	1,2,3, <u>1</u> /	1,2,3, <u>1/ 2</u> /
parameters (see 4.2)		4,5,6	4,5,6
Group A test	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3,4,5,6
requirements (see 4.4)			
Group C end-point electrical	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3, <u>2</u> /
parameters (see 4.4)			4,5,6
Group D end-point electrical	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3,4,5,6
parameters (see 4.4)			
Group E end-point electrical	1,4	1,4	1,4
parameters (see 4.4)			

TABLE IIA. Electrical test requirements.

1/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be completed with reference to the zero hour electrical parameters (see table I).

Parameters	Device type	Symbol	Test limits		Delta	limits	Units
			Min	Max	Min	Max	
ENABLE low threshold current	01, 02	IIL _{0V}		1	-1	+1	μΑ
ENABLE low threshold current	01, 02	IIL _{0.5V}		10	-2	+2	μΑ
ENABLE high threshold current	01, 02	IIH _{2V}		60	-4	+4	μΑ
ENABLE high threshold current	01, 02	IIH _{3V}		100	-7	+7	μΑ
ENABLE high threshold current	01, 02	IIH _{5V}		180	-9	+9	μA
3 V positive supply current	01, 02	I _{PS3V}	33	53	-4	+4	mA
5 V positive supply current	01, 02	I _{PS5V}	35	55	-4	+4	mA
Maximum positive supply ENABLE high	01, 02	IPSmax	35	55	-4	+4	mA
Positive supply current ENABLE low	01, 02	IStandby		20	-4	+4	μA

TABLE IIB. Burn-in and operating life test delta parameters. 1/2/

<u>1</u>/ Deltas are performed at room temperature.

2/ 240 hour burn-in and 1,000 hour operating group C life test.

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4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}C$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5°C, after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 <u>Total dose irradiation testing</u>. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A for device type 01, condition D for device type 02 and as specified herein.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 <u>Substitutability</u>. Device class Q devices will replace device class M devices.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime -VA, telephone (614) 692-0544.

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6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime -VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime -VA and have agreed to this drawing.

6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime -VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 11-10-04

Approved sources of supply for SMD 5962-09227 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at http://www.landandmaritime.dla.mil/Programs/Smcr/.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962R0922701VFA	24355	AD8346AF/QMLR
5962R0922701VXA	24355	AD8346AF/QMLR
5962L0922702VFA	<u>3</u> /	AD8346AF/QMLL
5962L0922702VXA	24355	AD8346AF/QMLL

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE <u>number</u> Vendor name and address

24355

Analog Devices Route 1 Industrial Park P.O. Box 9106 Norwood, MA 02062 Point of contact: 7910 Triad Center Drive Greensboro, NC 27409-9605

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